

Specification Page 5 - Amended without Underlining and Strikethroughs - Clean Version

are devoid of fusibility, it is possible to obtain the cleaning device of the present invention, so that material selection is possible from a wider range than in the prior art. Thus, according to the requisite specifications, such as the configuration and durability of the base material, and recycling property, it is possible to freely make material selection even from materials with no fusibility.

Further, a bonding system using an adhesive is adopted, so that even when the fibers and the base sheet are formed of different materials, it is possible to effect integral bonding of these members reliably and uniformly. Further, since it is possible to select the hardness of the adhesive, if a soft adhesive is adopted, there is no fear of thermal hardening of the bonding portion or damaging of the surface to be cleaned as in the case of the heat sealing system. Further, by using a hot melt type adhesive, it is possible to effect bonding by solely heating and cooling the materials to a relatively low temperature, thereby substantially reducing the processing time and the processing cost.

In the case of the conventional heat sealing system, the bonding portion, which is generally of a narrow and

linear configuration, undergoes concentrated heating and pressurization in order to melt the materials to be heat-sealed to a sufficient degree and to effect heat sealing without involving any spots. Thus, in the case of the conventional heat sealing system, in particular, in which the base